Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1702-01** DATE: **2-May-2017**

Product Affected: 13.0mm x 13.0mm x 1.53mm CABGA-144
15.0mm x 15.0mm x 1.53mm CABGA-196
15.0mm x 15.0mm x 1.68mm CABGA-196
Refer to Attachment II for the affected part numbers

Date Effective: **2-Aug-2017**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ■ Other — Materials used is traceable through Assembly Lot#

Contact: IDT PCN DESK

E-mail: pcndesk@idt.com

Attachment: ■ Yes ☐ No

Samples: Please contact your local sales representative for sample request & availability.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ■ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ■ Other - MSL Rating

This notification is to advise our customers that the mold conpound material and solder paste material will be changed to GE100RFC32 and SnSb respectively.

There is a change on the moisture performance from MSL 4 to MSL 3 for 15.0mm x 15.0mm x 1.53mm CABGA-196. No change in MSL rating for the other packages.

Attachment I details the qualification data for this change and Attachment II shows the affected list of part numbers.

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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ATTACHMENT I - PCN # : A1702-01

PCN Type: Change of Materials

Data Sheet Change: Change in moisture sensitivity level (MSL) from 4 to 3 on 15.0mm x 15.0mm x 1.53mm CABGA-196

Detail Of Change:

This notification is to advise our customers that the mold conpound material and solder paste material will be changed to GE100RFC32 and SnSb respectively.

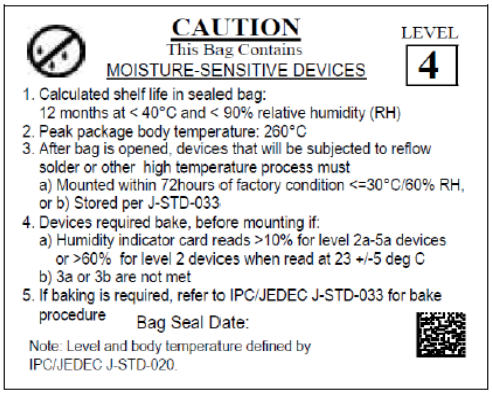
There is a change on the moisture performance from MSL 4 to MSL 3 for 15.0mm x 15.0mm x 1.53mm CABGA-196. No change in MSL rating for the other packages. The affected products will be shipped with dry pack and labeled as MSL 3 according to JEDEC J-STD-020. The peak reflow temperature remain unchanged at 260°C. Refer to Attachment I for the examples of moisture sensitive labels.

Change of Material Set

Description	From	To
Mold Compound Material	GE100RFC	GE100RFC32
Solder Paste Material	SnAg	SnSb

MSL Rating Changes on 15.0mm x 15.0mm x 1.53mm CABGA-196

From: MSL 4 Moisture Sensitive Label



To: MSL 3 Moisture Sensitive Label

Note: There is no change to the peak reflow temperature of the affected products.

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Qualification Test Plans and Results :

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests

Qual Vehicle: 15.0mm x 15.0mm x 1.53mm CABGA-196 (3 lots)

		Test Results (SS / Rej)		
Test Description	**Test Method**	**Lot 1**	**Lot 2**	**Lot 3**
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0
Moisture Classification (Level 3 @ 260 °C)	J-STD-020C	25/0	-	25/0

Note:
* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test

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ATTACHMENT II - PCN # : A1702-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
8V89317BAG8	82V3910AUG-MV	82P33910-1BAG	82P33810BAG
82P33931BAG/W	8V89317BAG	82P33810ABAG	82P33831YBBAG
82P33931BAG	8V89316BAG8	82P33741BAG8	82P33831YABAG
82P33931-1BAG8	8V89316BAG	82P33741BAG	82P33831BAG8
82P33931-1BAG/W	82V3912AUG8	82P33731BAG8	82P33831BAG
82P33931-1BAG	82V3912AUG	82P33731BAG	82P33831ABAG8
82P33910BAG8	82V3911AUG8	82P33731ABAG8	82P33831ABAG/W
82P33910BAG/W	82V3911AUG	82P33731ABAG	82P33831ABAG
82P33910BAG	82V3910AUG8	82P33710BAG8	82P33810BAG8
82P33931BAG8	82P33910-1BAG8	82P33810ABAG/W	82P33710BAG
82V3910AUG	82P33910-1BAG/W	82P33810ABAG8	